

ABSTRACT OF THE DISCLOSURE

A multi-heatsink integrated cooler for direct cooling of at least two electronic components comprises at least two heatsinks with heat-exchanging means and housings with inflow and outflow openings and one common blower. Each of the heatsinks is located independently in tight contact with one of said electronic components. The housings of all said heatsinks are hydraulically connected in a common system of airflow between said heat-exchanging means of all the heatsinks and the inside space of said blower by at least one sealing element from the elastic material located in the clearance between nearest parts of said housings thus compensating the differences in locations and tolerances. The cooler comprises the radial blower located overlapping at least one of said heatsinks so that an inlet of said blower is coincided with the outflow opening of said common system of airflow. Said blower is located directly on the surface of one of said heatsinks overlapping at least one another heatsink.